Fast Recovery Diode

DA2JF2300L

Panasonic

DA2JF2300L

Silicon epitaxial planar type

For high speed switching circuits

■ Features

- · Small reverse current IR
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)
- Marking Symbol: 4A

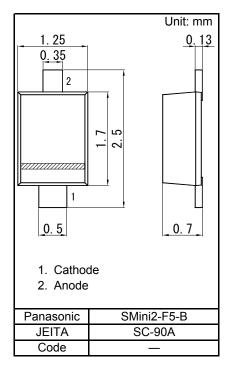
Established: 2010-03-31

: 2013-05-29

Revised

■ Packaging

Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)



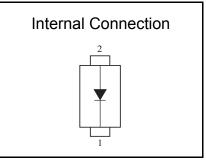
■ Absolute Maximum Ratings Ta = 25 °C

Parameter	Symbol	Rating	Unit
Repetitive peak reverse voltage	VRRM	300	V
Non-repetitive peak reverse surge voltage	VRSM	300	V
Forward current (Average) *1	IF(AV)	0.3	Α
Non-repetitive peak forward surge current *2	IFSM	3.0	Α
Junction temperature	Tj	150	°C
Operating ambient temperature	Topr	-40 to +85	°C
Storage temperature	Tstg	-40 to +150	°C

Note) *1: temperature:Ta = 90°C, with DC wave and

Alumina PC board (Board: 20 mm×50 mm, Soldering land: 2 mm×2 mm)

*2: 50 Hz sine wave 1 cycle (Non-repetitive peak current)



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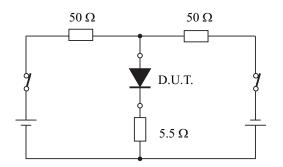
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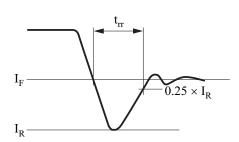
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■ Electrical Characteristics Ta = 25 °C ± 3 °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	VF	IF = 300 mA			1.25	V
Reverse current	IRRM	VRRM = 300 V			1.0	μA
Terminal capacitance	Ct	VR = 0 V, f = 1 MHz		3.5		pF
Reverse recovery time *1	trr	IF = 100 mA, IR = 200mA Irr = 0.25 x IR		400		ns
Thermal resistance(ch-a) *2	Rth(j-a)	Mounted on an alumina PC board		160		°C/W

- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031measuring methods for diodes.
 - 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
 - 3. Absolute frequency of Input and output is 20 MHz
 - 4. *1 trr measurement circuit



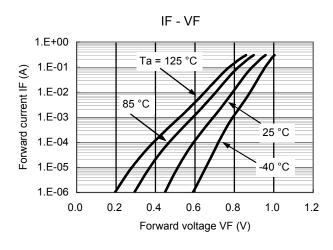


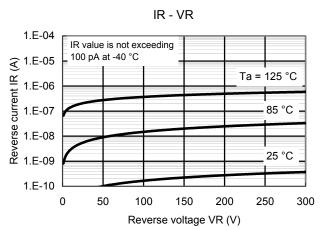
 $^{\star}2$ Mounted on an alumina PC board (Board: 20 mm×50 mm, Soldering land: 2 mm×2 mm)

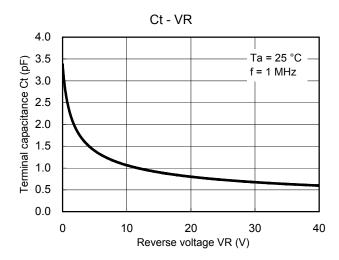
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Technical Data (reference)







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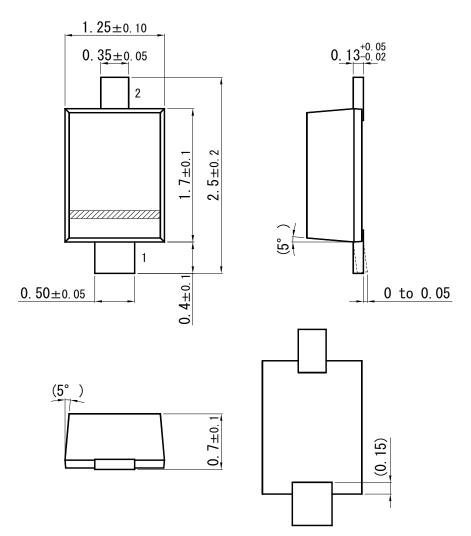
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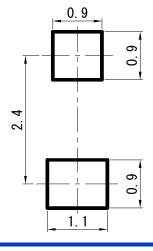
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SMini2-F5-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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